NEC Electronics Inc.

μPD424266
262,144 x 4-Bit
Dynamic CMOS RAM

Description

The μPD424266 is a 262,144 by 4-bit dynamic RAM designed with a write-per-bit option and to operate from a single + 5-volt power supply. Advanced polycide technology using trench capacitors minimizes silicon area and provides high storage cell capacity, high performance, and high reliability. A single-transistor dynamic storage cell and CMOS circuitry throughout ensure minimum power dissipation, while an on-chip circuit internally generates the negative-voltage substrate bias—automatically and transparently.

The three-state I/O pins are controlled by $\overline{CAS}$ independent of $\overline{RAS}$. After a valid read or read-modify-write cycle, data is held on the outputs by maintaining $\overline{CAS}$ low. Data outputs return to high impedance when $\overline{CAS}$ goes high. Fast-page read and write cycles can be executed by cycling $\overline{CAS}$.

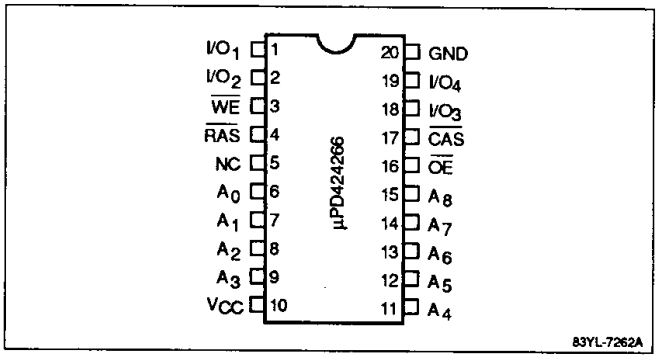
Refreshing may be accomplished by means of a $\overline{CAS}$ before $\overline{RAS}$ cycle that internally generates the refresh address. Refreshing may also be accomplished by means of $\overline{RAS}$-only refresh cycles or by normal read or write cycles on the 512 address combinations of A_0 through A_8 during an 8-ms refresh period.

Features

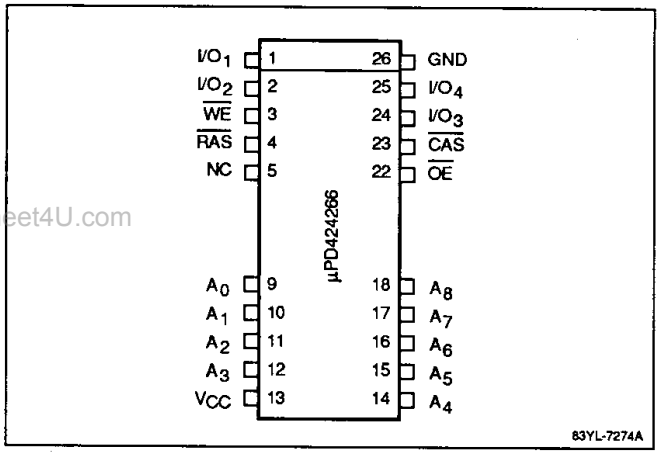
- 262,144 by 4-bit organization
- Single + 5-volt power supply
- Write-per-bit option
- Fast-page option
- Low power dissipation
- $\overline{CAS}$ before $\overline{RAS}$ internal refreshing
- Multiplexed address inputs
- On-chip substrate bias generator
- TTL-compatible inputs and outputs
- Nonlatched, three-state outputs
- Low input capacitance
- 512 refresh cycles every 8 ms
- High-density 20-pin plastic DIP, 26/20-pin plastic SOJ, or 20-pin plastic ZIP packaging

Pin Configurations

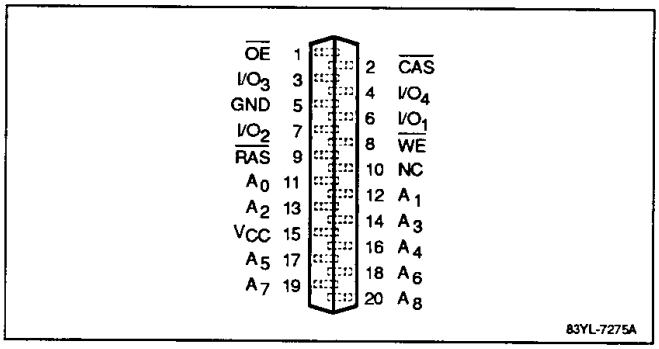
20-Pin Plastic DIP



26/20-Pin Plastic SOJ



20-Pin Plastic ZIP



6

Pin Identification

Name	Function
A_0 - A_8	Address inputs
I/O_1 - I/O_4	Data inputs and outputs
$\overline{CAS}$	Column address strobe
$\overline{OE}$	Output enable
$\overline{RAS}$	Row address strobe
$\overline{WE}$	Write enable
GND	Ground
V_{CC}	+5-volt power supply
NC	No connection

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Input voltage, high	V_{IH}	2.4		V_{CC} + 1.0	V
Input voltage, low	V_{IL}	−1.0		0.8	V
Supply voltage	V_{CC}	4.5	5.0	5.5	V
Ambient temperature	T_A	0		70	°C

Capacitance

T_A = 25°C; f = 1 MHz

Parameter	Symbol	Max	Unit	Pins Under Test
Input capacitance	C_{I1}	5	pF	Addresses
	C_{I2}	7	pF	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$
Input/output capacitance	C_{IO}	7	pF	I/O_1 – I/O_4

Absolute Maximum Ratings

Voltage on any pin relative to GND, V_T	−1.0 to +7.0 V
Operating temperature, T_{OPR}	0 to +70°C
Storage temperature, T_{STG}	−55 to +125°C
Short-circuit output current, I_{OS}	50 mA
Power dissipation, P_D	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Ordering Information

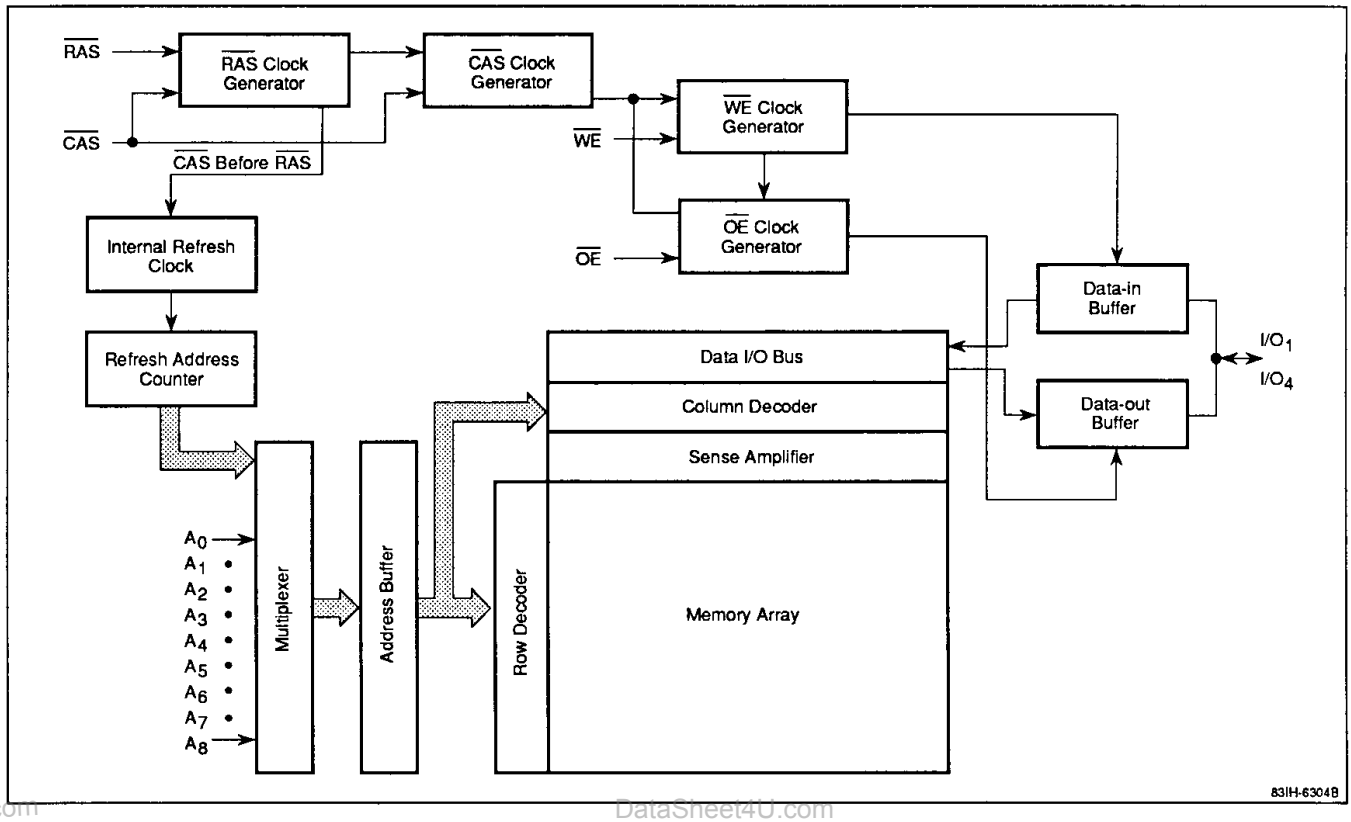
Part Number	$\overline{RAS}$ Access Time (max)	R/W Cycle Time (max)	Fast-Page Cycle (max)	Package
μPD424266C-60	60 ns	120 ns	40 ns	20-pin plastic DIP
C-70	70 ns	130 ns	45 ns	
C-80	80 ns	160 ns	50 ns	
C-10	100 ns	190 ns	60 ns	
μPD424266LA-60	60 ns	120 ns	40 ns	26/20-pin plastic SOJ
LA-70	70 ns	130 ns	45 ns	
LA-80	80 ns	160 ns	50 ns	
LA-10	100 ns	190 ns	60 ns	
μPD424266V-60	60 ns	120 ns	40 ns	20-pin plastic ZIP
V-70	70 ns	130 ns	45 ns	
V-80	80 ns	160 ns	50 ns	
V-10	100 ns	190 ns	60 ns	

DC Characteristics

T_A = 0 to +70°C; V_{CC} = +5.0 ±10%

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	I_{CC2}			2.0	mA	$\overline{RAS}$ ≥ V_{IH} (min); I_O = 0 mA
				1.0	mA	$\overline{RAS}$ = $\overline{CAS}$ ≥ V_{CC} – 0.2 V; I_O = 0 mA
Input leakage current	$I_{I(L)}$	−10		10	μA	V_{IN} = 0 V to V_{CC}; all other pins not under test = 0 V
Output leakage current	$I_{O(L)}$	−10		10	μA	D_{OUT} disabled; V_{OUT} = 0 V to V_{CC}
Output voltage, low	V_{OL}			0.4	V	I_{OL} = 4.2 mA
Output voltage, high	V_{OH}	2.4			V	I_{OH} = −5 mA

Block Diagram



6

AC Characteristics

T_A = 0 to +70°C; V_{CC} = +5.0 V ±10%

		-60		-70		-80		-10			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Test Conditions**
Operating current, average	I_{CC1}		90		80		70		60	mA	$\overline{RAS}$, $\overline{CAS}$ cycling; t_{RC} = t_{RC} min (Note 5)
Operating current, $\overline{RAS}$-only refresh cycle, average	I_{CC3}		90		80		70		60	mA	$\overline{RAS}$ cycling; $\overline{CAS}$ = V_{IH}; t_{RC} = t_{RC} min (Note 5)
Operating current, fast-page cycle, average	I_{CC4}		80		70		60		50	mA	$\overline{RAS}$ = V_{IL}; $\overline{CAS}$ cycling; t_{PC} = t_{PC} min (Note 5)
Operating current, $\overline{CAS}$ before $\overline{RAS}$ refresh cycle, average	I_{CC5}		90		80		70		60	mA	$\overline{RAS}$ cycling; $\overline{CAS}$ before $\overline{RAS}$; t_{RC} = t_{RC} min (Note 5)
Access time from column address	t_{AA}		30		35		40		50	ns	(Notes 7, 10)
Access time from $\overline{CAS}$ precharge (rising edge)	t_{ACP}		35		40		45		55	ns	(Notes 7)
Column address setup time	t_{ASC}	0		0		0		0		ns	
Row address setup time	t_{ASR}	0		0		0		0		ns	
Column address to $\overline{WE}$ delay time	t_{AWD}	50		55		65		80		ns	(Note 17)

AC Characteristics (cont)

Parameter	Symbol	-60 Min	-60 Max	-70 Min	-70 Max	-80 Min	-80 Max	-10 Min	-10 Max	Unit	Test Conditions
Access time from $\overline{CAS}$ (falling edge)	t_{CAC}		20		20		20		25	ns	(Notes 7, 9, 10)
Column address hold time	t_{CAH}	15		17		20		20		ns	
$\overline{CAS}$ pulse width	t_{CAS}	20	10,000	20	10,000	20	10,000	25	10,000	ns	
$\overline{CAS}$ hold time for $\overline{CAS}$ before $\overline{RAS}$ refresh cycle	t_{CHR}	15		15		15		20		ns	
$\overline{CAS}$ precharge time, fast-page cycle	t_{CP}	10		10		10		10		ns	
$\overline{CAS}$ precharge time, nonpage cycle	t_{CPN}	10		10		10		10		ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	10		10		10		10		ns	(Note 13)
$\overline{CAS}$ hold time	t_{CSH}	60		70		80		100		ns	
$\overline{CAS}$ setup time for $\overline{CAS}$ before $\overline{RAS}$ refresh cycle	t_{CSR}	10		10		10		10		ns	
$\overline{CAS}$ to $\overline{WE}$ delay	t_{CWD}	40		40		45		55		ns	(Note 17)
Write command to $\overline{CAS}$ lead time	t_{CWL}	15		15		20		20		ns	
Data-in hold time	t_{DH}	15		15		20		20		ns	(Note 16)
Data-in setup time	t_{DS}	0		0		0		0		ns	(Note 16)
Access time from $\overline{OE}$	t_{OEA}		20		20		20		25	ns	
$\overline{OE}$ data delay time	t_{OED}	15		15		20		25		ns	
$\overline{OE}$ command hold time	t_{OEH}	0		0		0		0		ns	
$\overline{OE}$ to $\overline{RAS}$ inactive setup time	t_{OES}	0		0		0		0		ns	
Output turnoff delay from $\overline{OE}$	t_{OEZ}	0	15	0	15	0	20	0	25	ns	(Note 11)
Output buffer turnoff delay	t_{OFF}	0	15	0	15	0	20	0	25	ns	(Note 11)
Fast-page cycle time	t_{PC}	40		45		50		60		ns	(Note 6)
Fast-page read-modify-write cycle time	t_{PRWC}	85		90		105		125		ns	(Note 6)
Access time from $\overline{RAS}$	t_{RAC}		60		70		80		100	ns	(Notes 7, 8)

AC Characteristics (cont)

Parameter	Symbol	-60 Min	-60 Max	-70 Min	-70 Max	-80 Min	-80 Max	-10 Min	-10 Max	Unit	Test Conditions
$\overline{RAS}$ to column address delay time	t_{RAD}	15	30	15	35	17	40	17	50	ns	(Note 10)
Row address hold time	t_{RAH}	10		10		12		12		ns	
Column address lead time referenced to $\overline{RAS}$ (rising edge)	t_{RAL}	30		35		40		50		ns	
$\overline{RAS}$ pulse width	t_{RAS}	60	10,000	70	10,000	80	10,000	100	10,000	ns	
$\overline{RAS}$ pulse width, fast-page cycle	t_{RASP}	60	100,000	70	100,000	80	100,000	100	100,000	ns	
Random read or write cycle time	t_{RC}	120		130		160		190		ns	(Note 6)
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	20	40	20	50	25	60	25	75	ns	(Note 12)
Read command hold time referenced to $\overline{CAS}$	t_{RCH}	0		0		0		0		ns	(Note 14)
Read command setup time	t_{RCS}	0		0		0		0		ns	
Refresh period	t_{REF}		8		8		8		8	ms	Addresses A_0 - A_8
$\overline{RAS}$ precharge time	t_{RP}	50		50		70		80		ns	
$\overline{RAS}$ precharge $\overline{CAS}$ hold time	t_{RPC}	10		10		0		0		ns	
Read command hold time referenced to $\overline{RAS}$	t_{RRH}	10		10		10		10		ns	(Note 14)
$\overline{RAS}$ hold time	t_{RSH}	20		20		20		25		ns	
Read-write cycle time	t_{RWC}	165		175		215		255		ns	(Note 6)
$\overline{RAS}$ to $\overline{WE}$ delay	t_{RWD}	80		90		105		130		ns	(Note 17)
Write command to $\overline{RAS}$ lead time	t_{RWL}	20		20		25		30		ns	
Rise and fall transition time	t_T	3	50	3	50	3	50	3	50	ns	(Note 4)
Write-per-bit hold time	t_{WBH}	10		10		10		10		ns	
Write-per-bit setup time	t_{WBS}	0		0		0		0		ns	
Write command hold time	t_{WCH}	15		15		15		20		ns	(Note 15)
Write command setup time	t_{WCS}	0		0		0		0		ns	(Note 16)

AC Characteristics (cont)

Parameter	Symbol	-60 Min	-60 Max	-70 Min	-70 Max	-80 Min	-80 Max	-10 Min	-10 Max	Unit	Test Conditions
Write-per-bit mask data hold time	t_{WH}	10		10		10		10		ns	
Write command pulse width	t_{WP}	15		15		15		20		ns	(Note 15)
Write-per-bit mask data setup time	t_{WS}	0		0		0		0		ns	

Notes:

(1) All voltages are referenced to GND.

(2) An initial pause of 100 μs is required after power-up, followed by any eight $\overline{RAS}$ cycles, before proper device operation is achieved.

(3) AC measurements assume t_T = 5 ns.

(4) V_{IH} (min) and V_{IL} (max) are reference levels for measuring the timing of input signals. Transition times are measured between V_{IH} and V_{IL}.

(5) I_{CC1}, I_{CC3}, I_{CC4}, and I_{CC5} depend on output loading and cycle rates. Specified values are obtained with the output open. I_{CC3} is measured assuming that all column address inputs are held at either a high level or a low level during $\overline{RAS}$-only refresh cycles. I_{CC4} is measured assuming that all column address inputs are switched only once during each fast-page cycle.

(6) The minimum specifications are used only to indicate the cycle time at which proper operation over the full temperature range (T_A = 0 to +70°C) is assured.

(7) Load = 2 TTL (–1 mA, +4 mA) loads and 100 pF (V_{OH} = 2.0 V, V_{OL} = 0.8 V).

(8) Assumes that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value in this table, t_{RAC} increases by the amount that t_{RCD} or t_{RAD} exceeds the value shown.

(9) Assumes that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max).

(10) If $t_{RAD} \geq t_{RAD}$ (max), then the access time is defined by t_{AA}.

(11) t_{OFF} (max) defines the time at which the output achieves the open-circuit condition and is not referenced to V_{OH} or V_{OL}.

(12) Operation within the t_{RCD} (max) limit assures that t_{RAC} (max) can be met. t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than t_{RCD} (max), then access time is controlled exclusively by t_{CAC}.

(13) The t_{CRP} requirement should be applicable for $\overline{RAS}$/$\overline{CAS}$ cycles preceded by any cycle.

(14) Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.

(15) Parameter t_{WP} is applicable for a delayed write cycle such as a read-write/read-modify-write cycle. For early write operation, both t_{WCS} and t_{WCH} must be met.

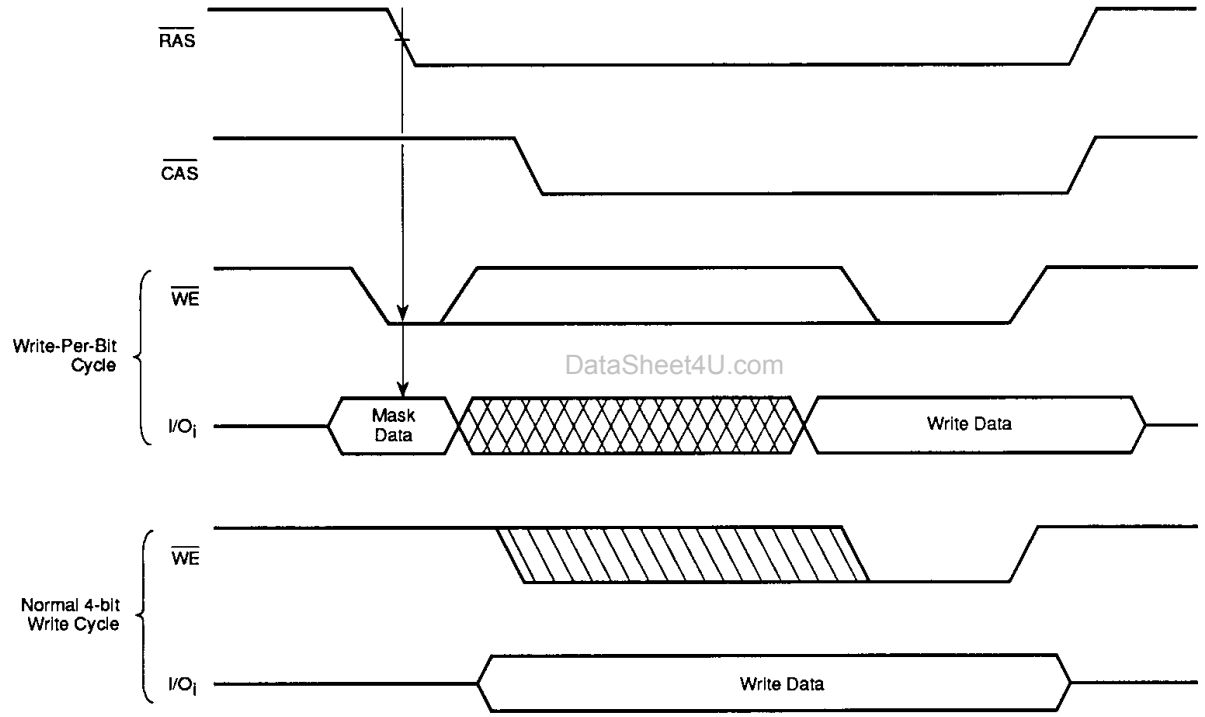
(16) These parameters are referenced to the falling edge of $\overline{CAS}$ for early write cycles and to the falling edge of $\overline{WE}$ for delayed write or read-modify-write cycles.

(17) t_{WCS}, t_{RWD}, t_{CWD}, and t_{AWD} are restrictive operating parameters in read-write/read-modify-write cycles only. If $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data output will remain open-circuit throughout the entire cycle. If $t_{CWD} \geq t_{CWD}$ (min), $t_{RWD} \geq t_{RWD}$ (min), and $t_{AWD} \geq t_{AWD}$ (min), the cycle is a read-write cycle and the data output will contain data read from the selected cell. If neither of the above conditions is met, the condition of the data output pin (at access time and until $\overline{CAS}$ returns to V_{IH}) is indeterminate.

Write-Per-Bit Option

The write-per-bit option may be used to allow a write cycle to change any number of bits in the 4-bit word. The mask is loaded from the four I/O lines at the falling edge of $\overline{RAS}$ if $\overline{WE}=V_{IL}$. If the I/O line is high, then the corresponding bit will be written when the write cycle executes. If an I/O line is low, the corresponding bit does not change. A mask loaded during fast-page operation will remain set and active for each write cycle that executes while $\overline{RAS}$ remains low. The mask may be changed at the falling edge of $\overline{RAS}$ only.

Comparison of Write-Per-Bit Cycle Versus Standard 4-Bit Write Cycle

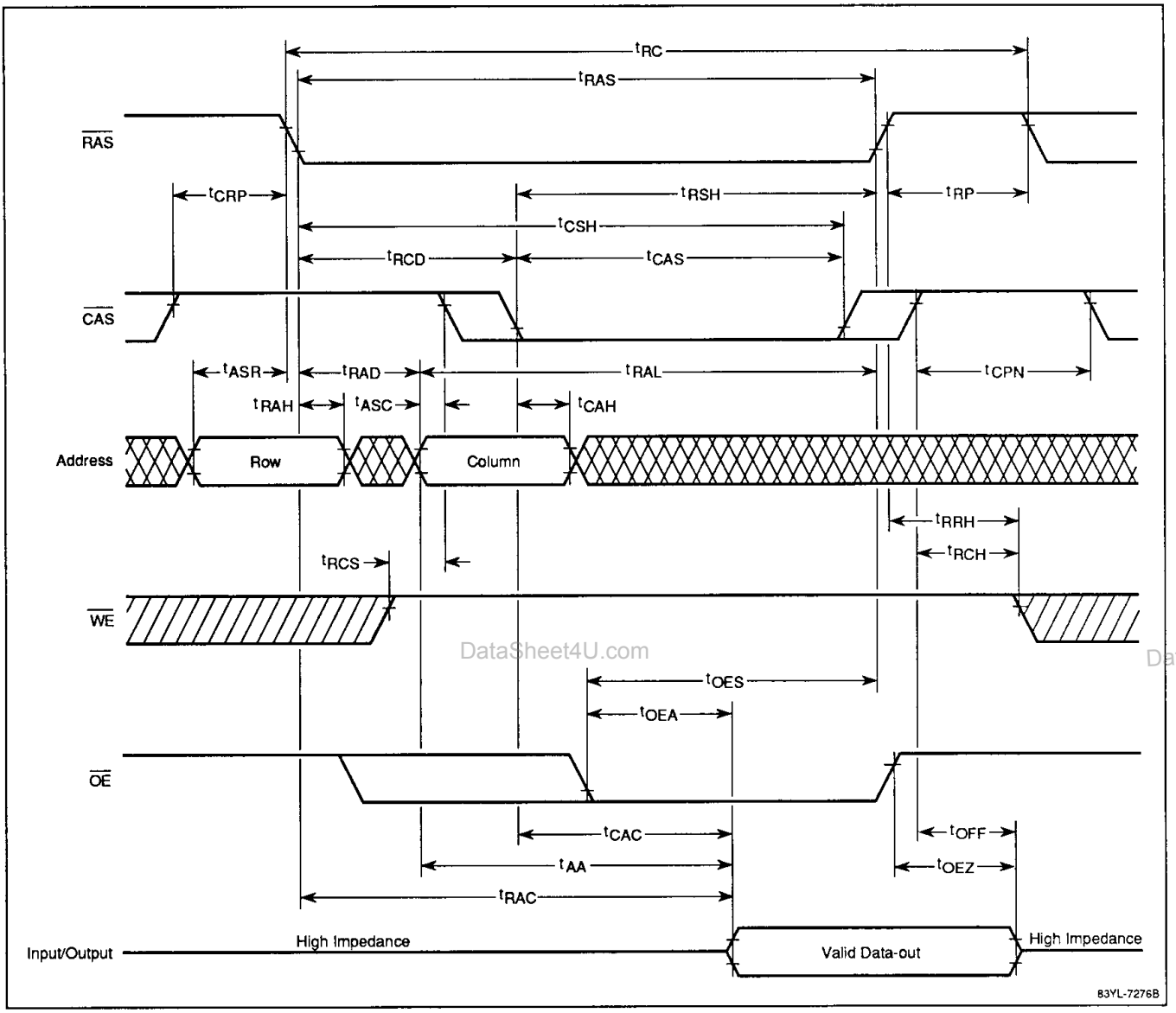


I/O	Mask Data		Write Operation
I/O_1	1	(High)	Write Bit
	0	(Low)	Disable Bit Write
I/O_2	1	(High)	Write Bit
	0	(Low)	Disable Bit Write
I/O_3	1	(High)	Write Bit
	0	(Low)	Disable Bit Write
I/O_4	1	(High)	Write Bit
	0	(Low)	Disable Bit Write

83VB-6778B

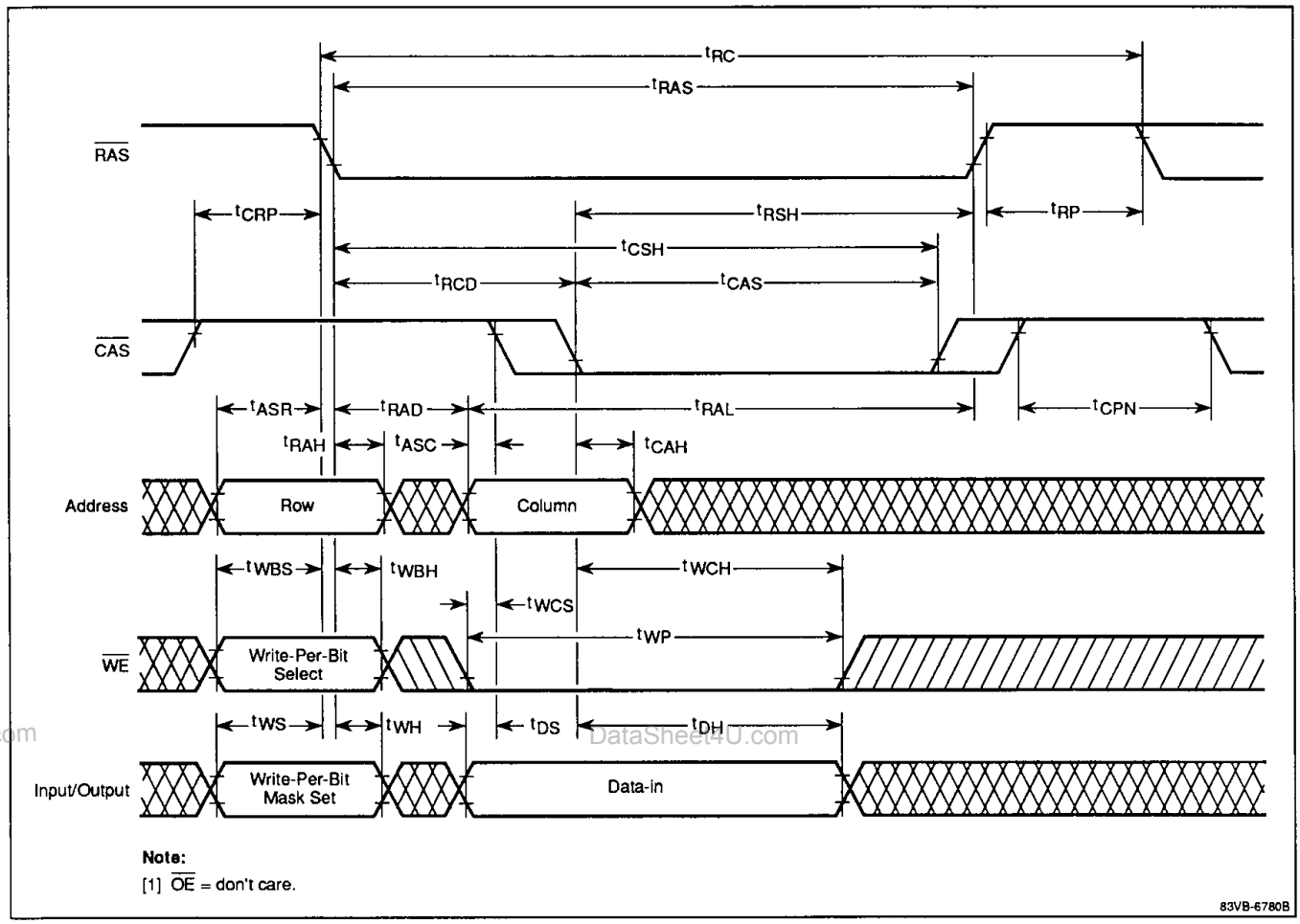
Timing Waveforms

Read Cycle



Timing Waveforms (cont)

Early Write Cycle

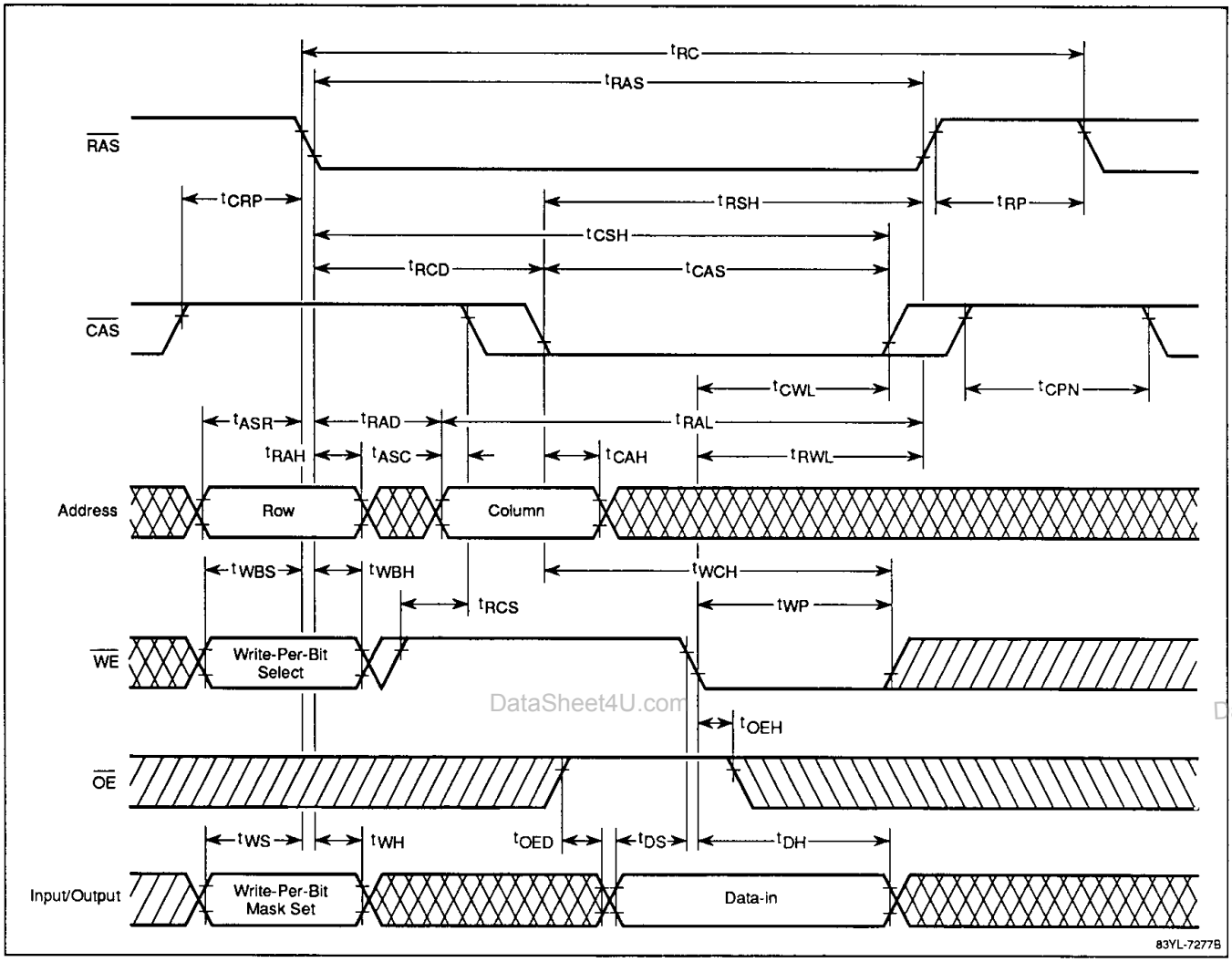


Note:
[1] $\overline{OE}$ = don't care.

83VB-6780B

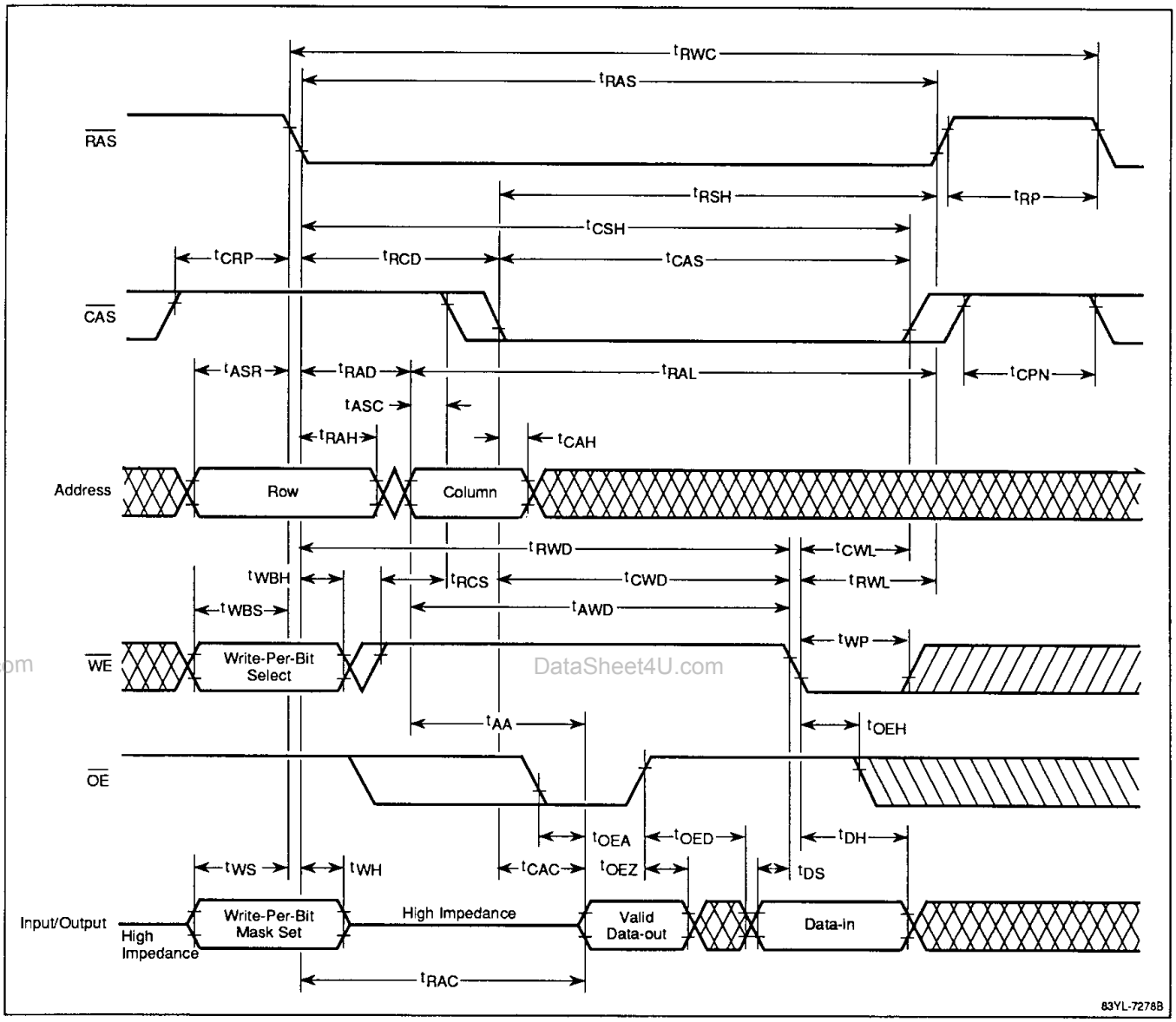
Timing Waveforms (cont)

Late Write Cycle



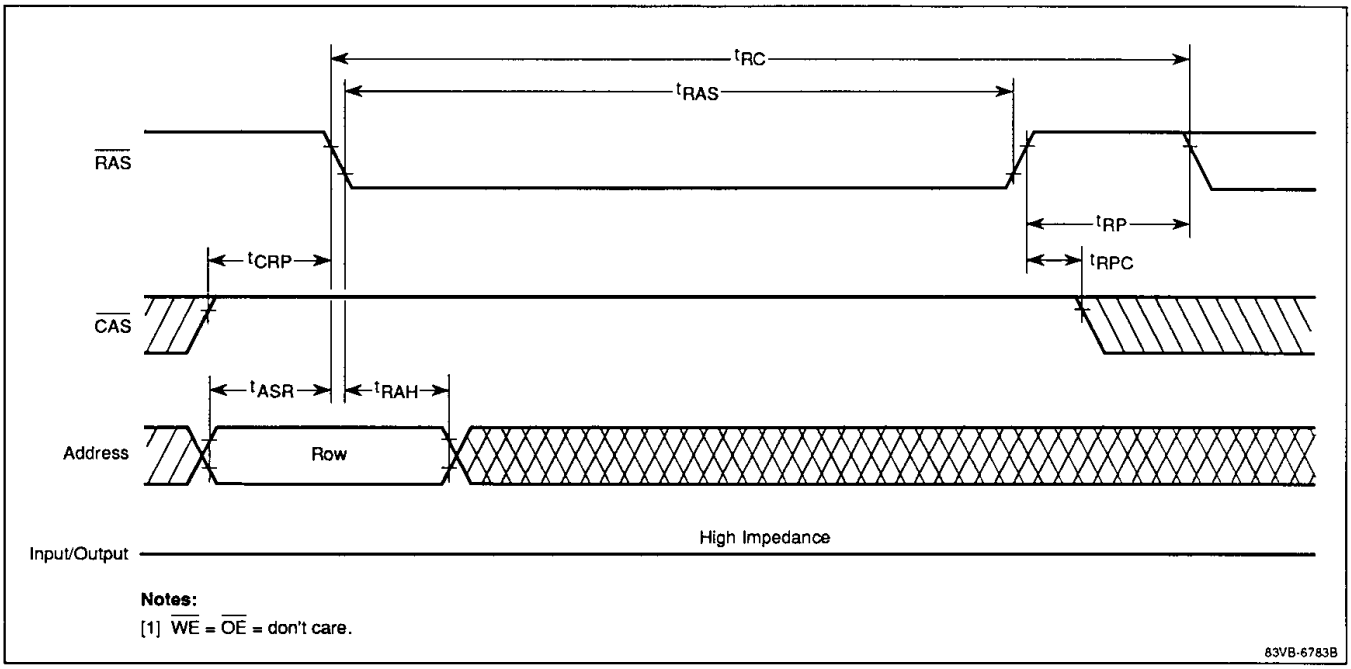
Timing Waveforms (cont)

Read-Write/Read-Modify-Write Cycle



Timing Waveforms (cont)

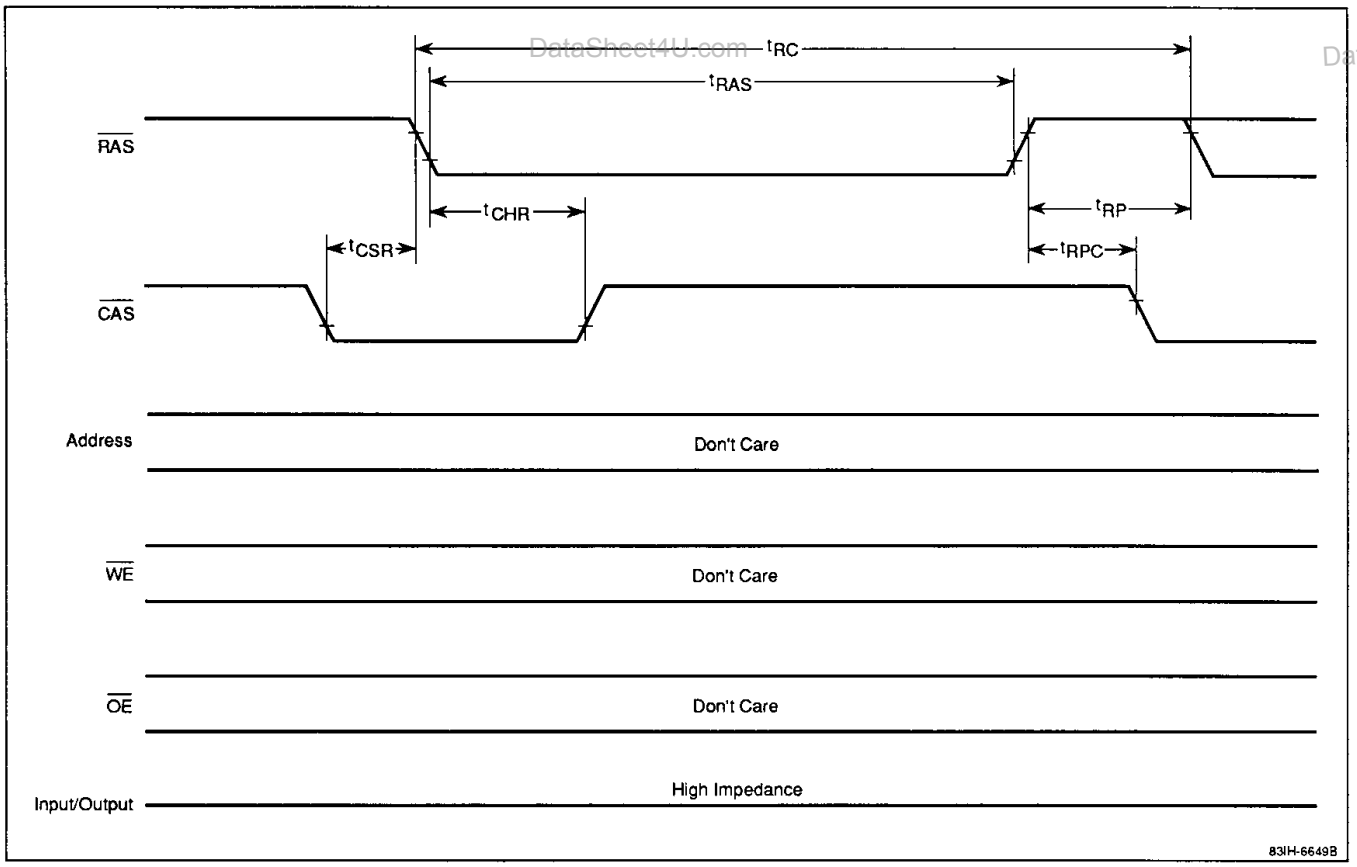
$\overline{RAS}$-Only Refresh Cycle



Notes:
[1] $\overline{WE}$ = $\overline{OE}$ = don't care.

83VB-6783B

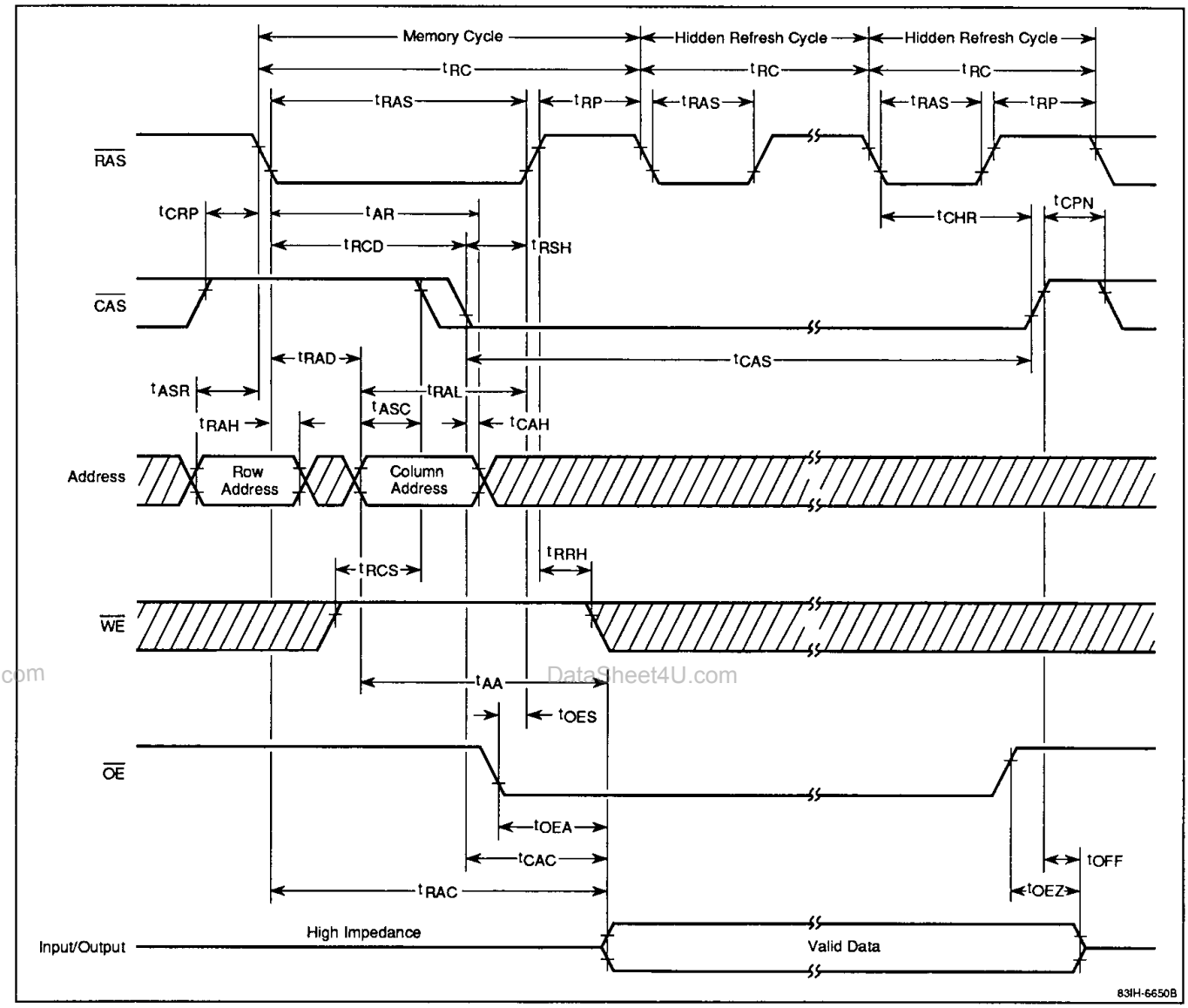
$\overline{CAS}$ Before $\overline{RAS}$ Refresh Cycle



83IH-6649B

Timing Waveforms (cont)

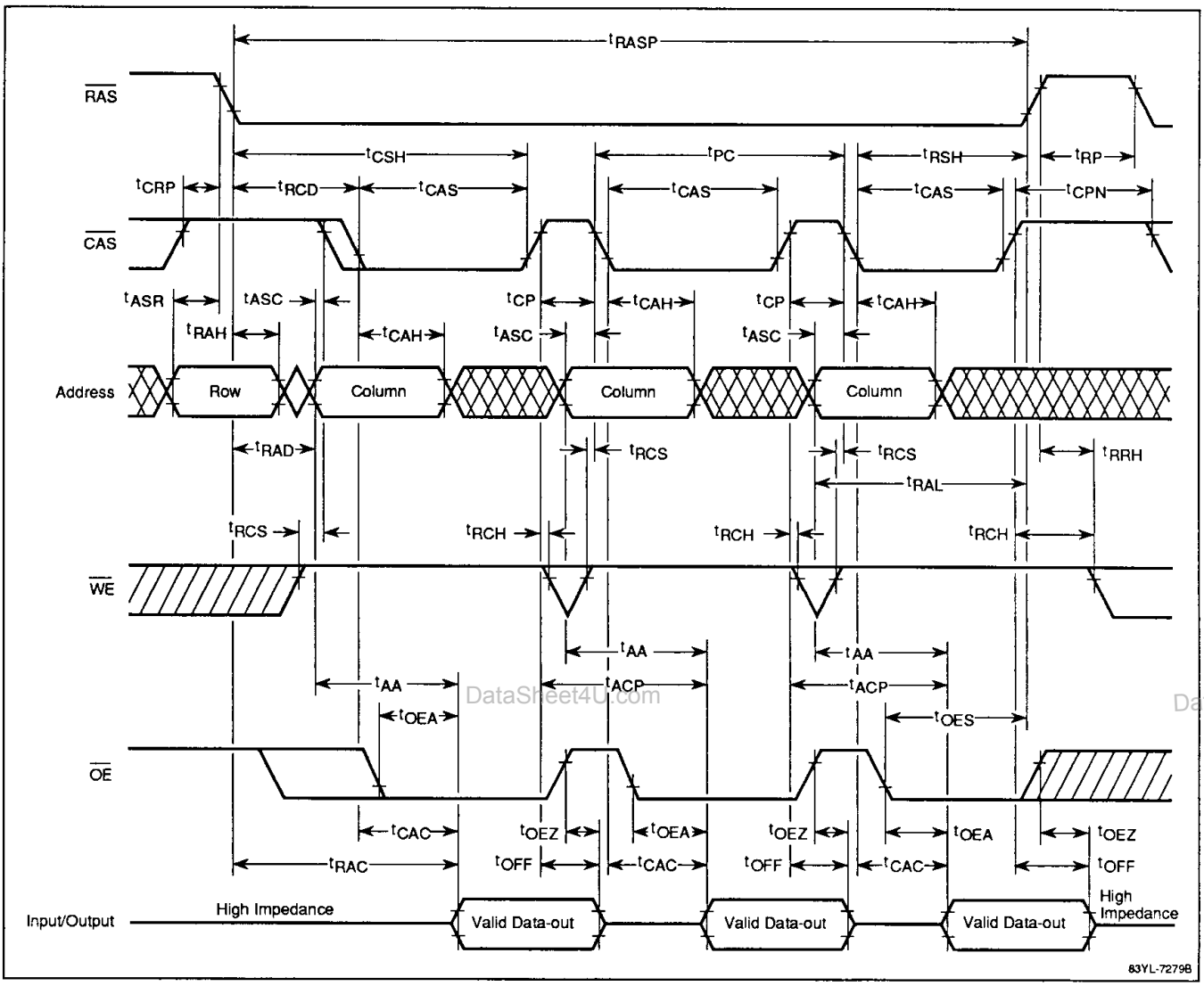
Hidden Refresh Cycle



6

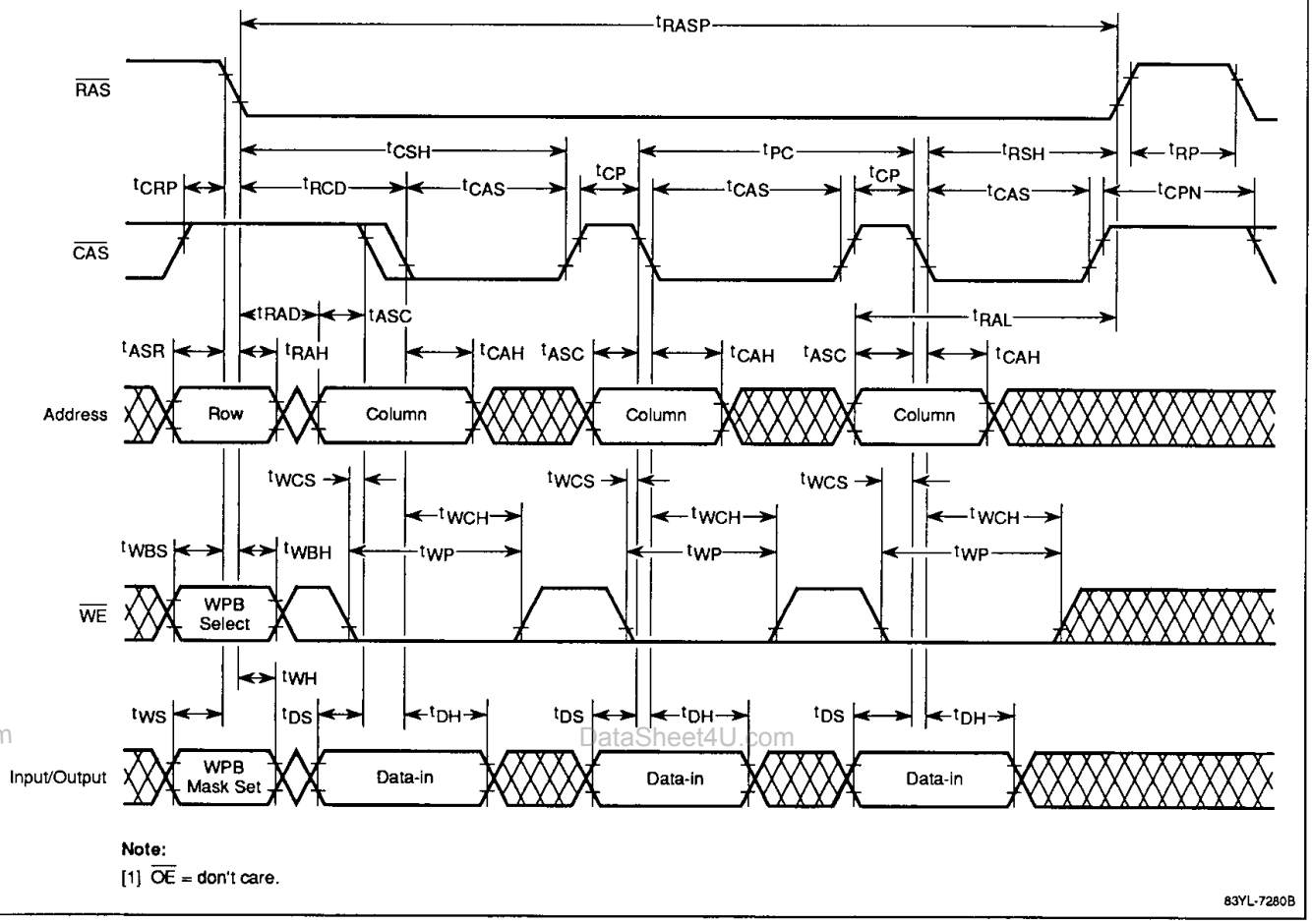
Timing Waveforms (cont)

Fast-Page Read Cycle



Timing Waveforms (cont)

Fast-Page Early Write Cycle



Note:

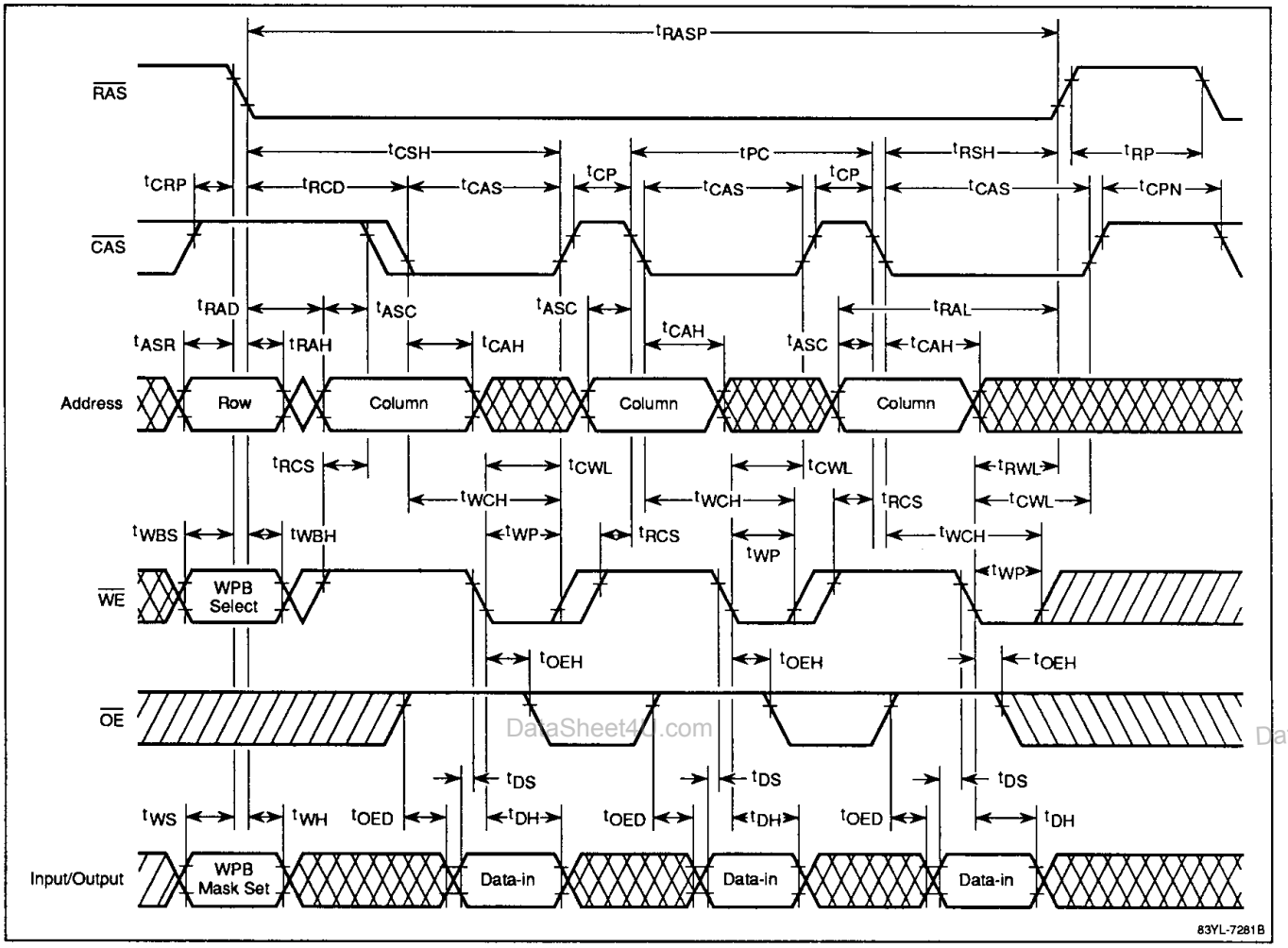
[1] $\overline{OE}$ = don't care.

83YL-7280B

6

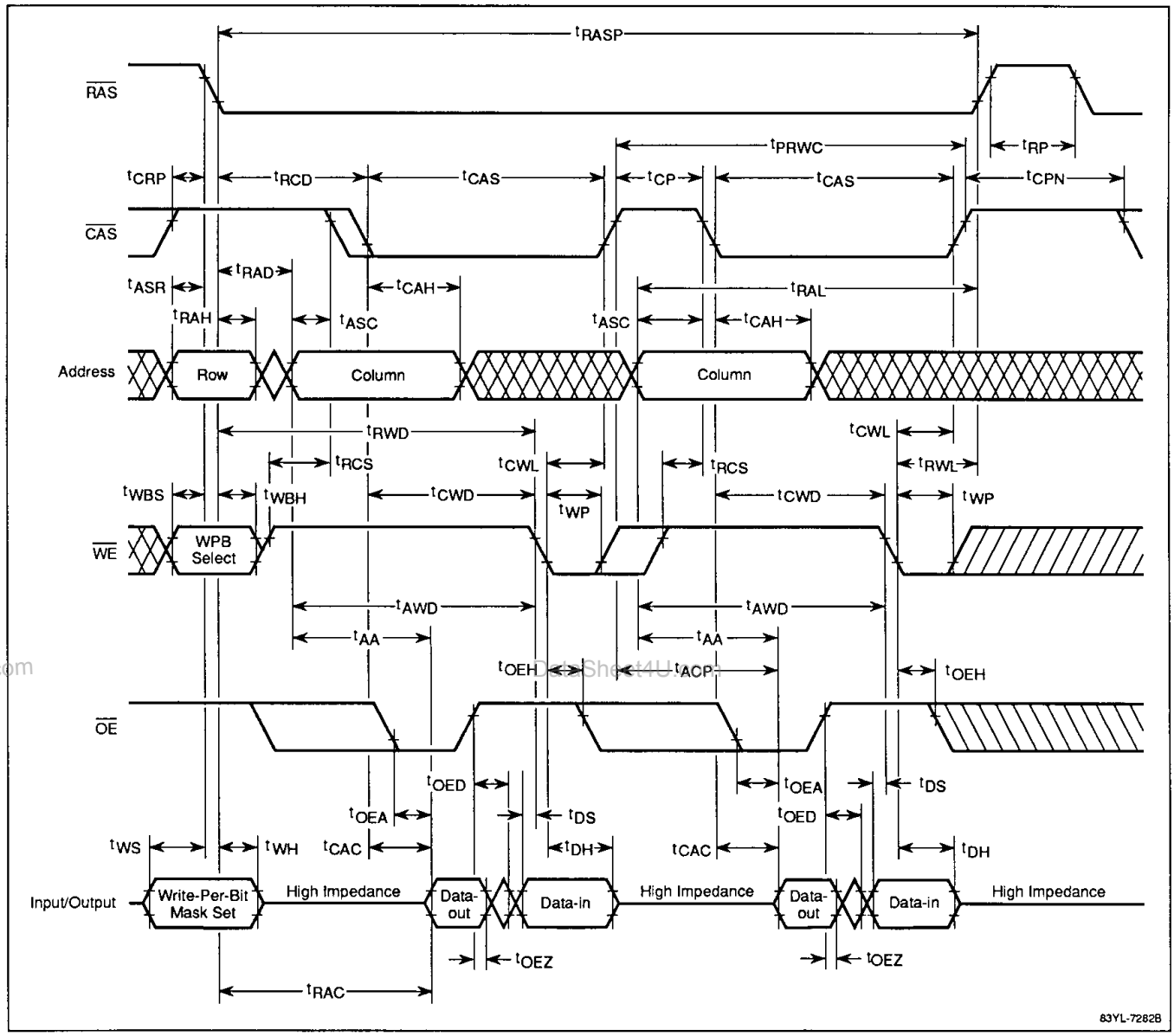
Timing Waveforms (cont)

Fast-Page Late Write Cycle



Timing Waveforms (cont)

Fast-Page Read-Write/Read-Modify-Write Cycle



6